

# 1 Electrical ratings

**Table 1. Absolute maximum ratings**

Symbol	Parameter	Value			Unit
		D <sup>2</sup> PAK, TO-220	TO-220FP	DPAK, IPAK	
V <sub>DS</sub>	Drain-source voltage	600			V
V <sub>GS</sub>	Gate-source voltage	±30			V
I <sub>D</sub>	Drain current (continuous) at T <sub>C</sub> = 25 °C	2.4	2.4 <sup>(1)</sup>	2.4	A
I <sub>D</sub>	Drain current (continuous) at T <sub>C</sub> = 100 °C	1.51	1.51 <sup>(1)</sup>	1.51	A
I <sub>DM</sub> <sup>(2)</sup>	Drain current (pulsed)	9.6	9.6 <sup>(1)</sup>	9.6	A
P <sub>TOT</sub>	Total dissipation at T <sub>C</sub> = 25 °C	45	20	45	W
ESD	Gate-source human body model (R = 1.5 kΩ, C = 100 pF)	2.1			kV
V <sub>ISO</sub>	Insulation withstand voltage (RMS) from all three leads to external heat-sink (t = 1 s, T <sub>C</sub> = 25 °C)	2.5			kV
dv/dt <sup>(3)</sup>	Peak diode recovery voltage slope	4.5			V/ns
T <sub>j</sub>	Operating junction temperature range	-55 to 150			°C
T <sub>stg</sub>	Storage temperature range				

- Limited by maximum junction temperature.
- Pulse width limited by safe operating area.
- I<sub>SD</sub> ≤ 2.4 A, di/dt ≤ 200 A/μs, V<sub>DSpeak</sub> ≤ V<sub>(BR)DSS</sub>. V<sub>DD</sub> = 80% V<sub>(BR)DSS</sub>.

**Table 2. Thermal data**

Symbol	Parameter	Value					Unit
		D <sup>2</sup> PAK	TO-220	TO-220FP	DPAK	IPAK	
R <sub>thj-case</sub>	Thermal resistance junction-case	2.78		6.25	2.78		°C/W
R <sub>thj-amb</sub>	Thermal resistance junction-ambient	62.5			100		°C/W
R <sub>thj-pcb</sub> <sup>(1)</sup>	Thermal resistance junction-pcb	35			50		°C/W

- When mounted on an 1-inch<sup>2</sup> FR-4, 2oz Cu board.

**Table 3. Avalanche characteristics**

Symbol	Parameter	Value	Unit
I <sub>AR</sub>	Avalanche current, repetitive or not-repetitive (pulse width limited by T <sub>j</sub> Max)	2.4	A
E <sub>AS</sub>	Single pulse avalanche energy (starting T <sub>j</sub> = 25 °C, I <sub>D</sub> = I <sub>AR</sub> , V <sub>DD</sub> = 50 V)	150	mJ

## 2 Electrical characteristics

( $T_{CASE} = 25\text{ °C}$  unless otherwise specified)

**Table 4. On/off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 1\text{ mA}$ , $V_{GS} = 0\text{ V}$	600			V
$I_{DSS}$	Zero gate voltage drain current	$V_{GS} = 0\text{ V}$ , $V_{DS} = 600\text{ V}$			1	$\mu\text{A}$
		$V_{GS} = 0\text{ V}$ , $V_{DS} = 600\text{ V}$ , $T_C = 125\text{ °C}$ <sup>(1)</sup>			50	$\mu\text{A}$
$I_{GSS}$	Gate body leakage current	$V_{DS} = 0\text{ V}$ , $V_{GS} = \pm 20\text{ V}$			$\pm 10$	$\mu\text{A}$
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$ , $I_D = 50\text{ }\mu\text{A}$	3	3.75	4.5	V
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 10\text{ V}$ , $I_D = 1.2\text{ A}$		3.2	3.6	$\Omega$

1. Defined by design, not subject to production test.

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 25\text{ V}$ , $f = 1\text{ MHz}$ , $V_{GS} = 0\text{ V}$	-	311	-	$\mu\text{F}$
$C_{oss}$	Output capacitance			43		
$C_{rSS}$	Reverse transfer capacitance			8		
$C_{oss\text{ eq.}}^{(1)}$	Equivalent output capacitance	$V_{DS} = 0\text{ to }480\text{ V}$ , $V_{GS} = 0\text{ V}$	-	26	-	$\mu\text{F}$
$Q_g$	Total gate charge	$V_{DD} = 480\text{ V}$ , $I_D = 2.4\text{ A}$ , $V_{GS} = 0\text{ to }10\text{ V}$ (see Figure 16. Test circuit for gate charge behavior)	-	11.8	-	nC
$Q_{gs}$	Gate-source charge			2.6		
$Q_{gd}$	Gate-drain charge			6.4		

1.  $C_{oss\text{ eq.}}$  is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$ .

**Table 6. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 300\text{ V}$ , $I_D = 1.5\text{ A}$ , $R_G = 4.7\text{ }\Omega$ , $V_{GS} = 10\text{ V}$ (see Figure 15. Test circuit for resistive load switching times and Figure 20. Switching time waveform)	-	9	-	ns
$t_r$	Rise time			14		
$t_{d(off)}$	Turn-off delay time			19		
$t_f$	Fall time			14		

**Table 7. Source drain diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		2.4	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)				9.6	
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 2.4 \text{ A}, V_{GS} = 0 \text{ V}$	-		1.6	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 2.4 \text{ A}, di/dt = 100 \text{ A}/\mu\text{s}$	-	306		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 48 \text{ V}, T_j = 150^\circ\text{C}$ (see <a href="#">Figure 17. Test circuit for inductive load switching and diode recovery times</a> )		948		nC
$I_{RRM}$	Reverse recovery current			6.2		A

1. Pulse width limited by safe operating area.
2. Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%.

**Table 8. Gate-source Zener diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)GSO}$	Gate-source breakdown voltage	$I_{GS} = \pm 1 \text{ mA}, I_D = 0 \text{ A}$	$\pm 30$	-	-	V

The built-in back-to-back Zener diodes are specifically designed to enhance the ESD performance of the device. The Zener voltage facilitates efficient and cost-effective device integrity protection, thus eliminating the need for additional external componentry.

## 2.1 Electrical characteristics curves

Figure 1. Safe operating area

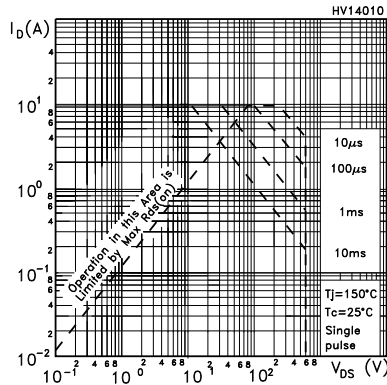


Figure 2. Thermal impedance

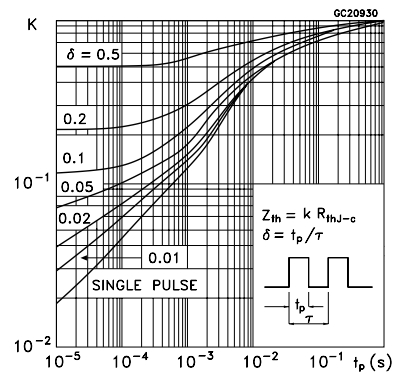


Figure 3. Safe operating area for TO-220FP

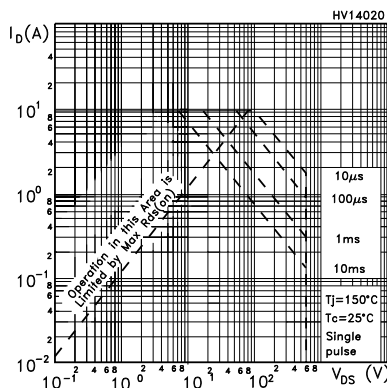


Figure 4. Thermal impedance for TO-220FP

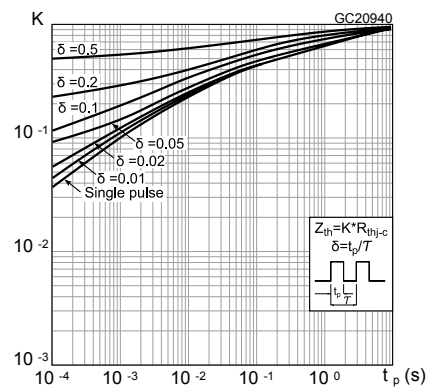


Figure 5. Output characteristics

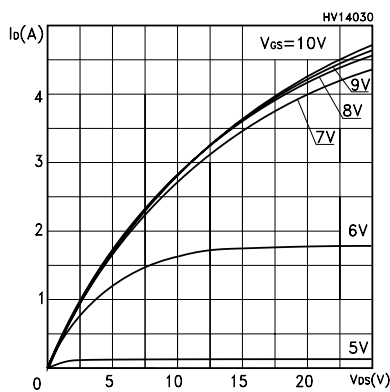


Figure 6. Transfer characteristics

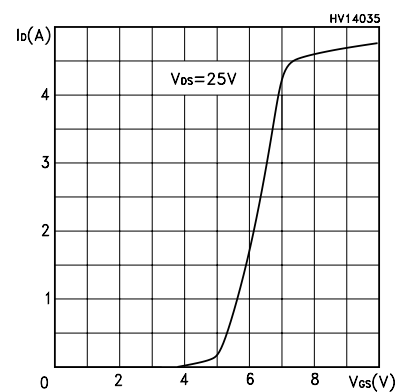


Figure 7. Static drain-source on resistance

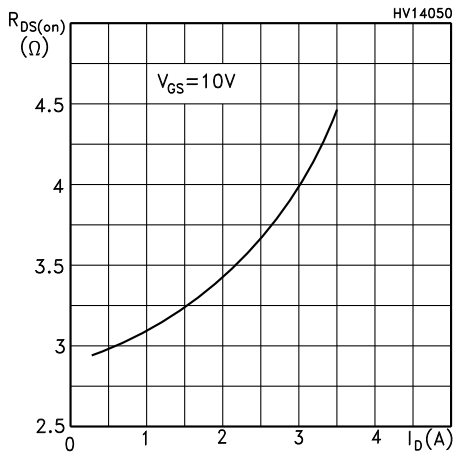


Figure 8. Gate charge vs gate-source voltage

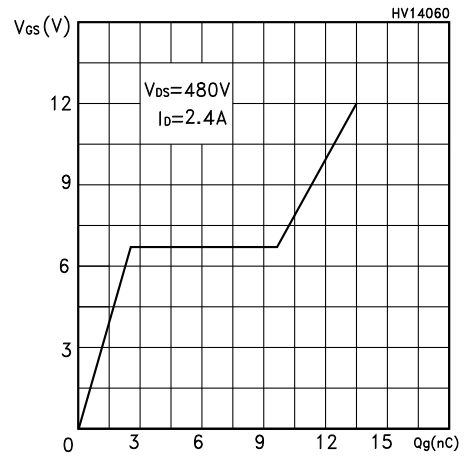


Figure 9. Capacitance variations

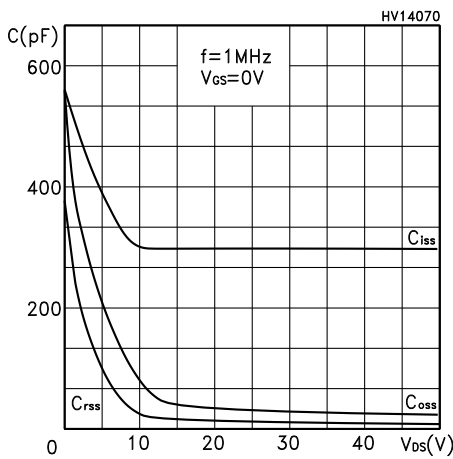


Figure 10. Normalized gate threshold voltage vs temperature

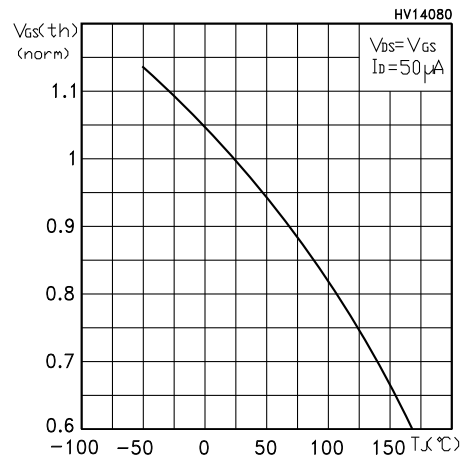


Figure 11. Normalized on resistance vs temperature

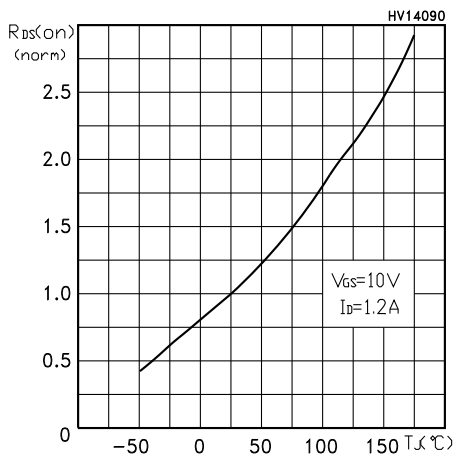


Figure 12. Source-drain diode forward characteristic

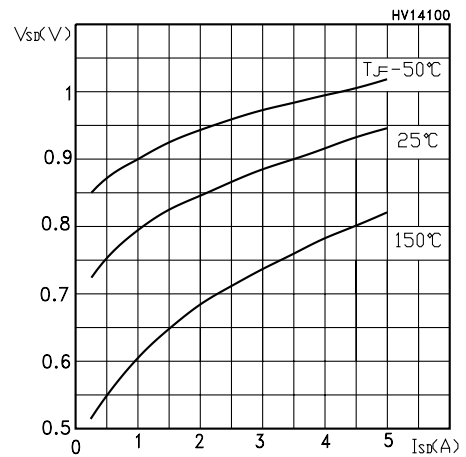


Figure 13. Normalized  $V_{(BR)DSS}$  vs temperature

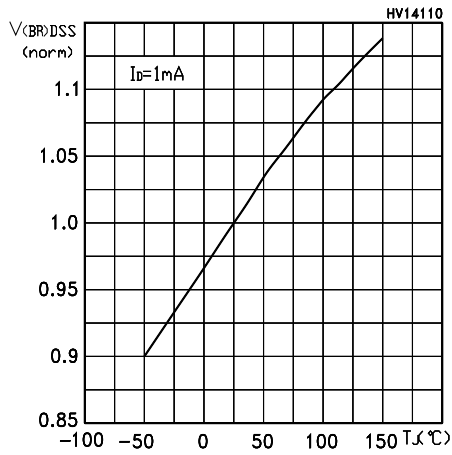
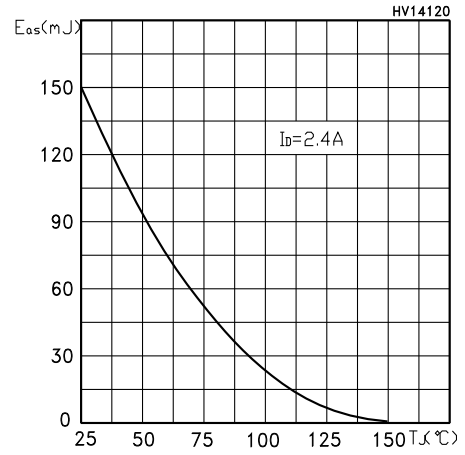
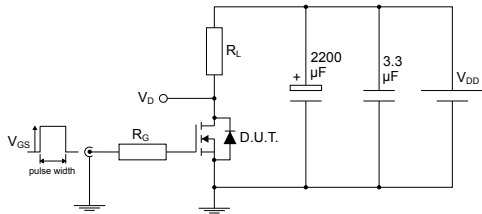


Figure 14. Maximum avalanche energy vs temperature



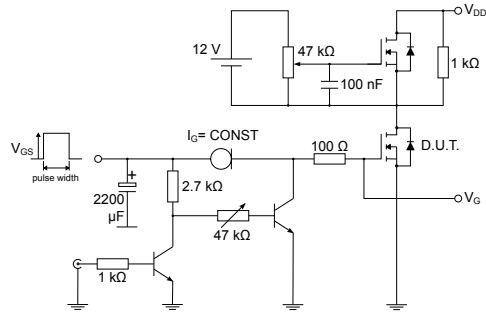
### 3 Test circuits

Figure 15. Test circuit for resistive load switching times



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Figure 16. Test circuit for gate charge behavior



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Figure 17. Test circuit for inductive load switching and diode recovery times



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Figure 18. Unclamped inductive load test circuit



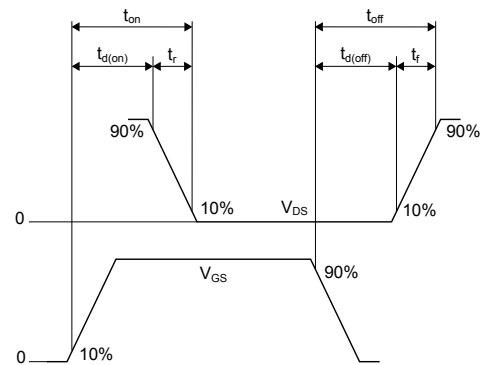
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Figure 19. Unclamped inductive waveform



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Figure 20. Switching time waveform



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## 4 Package information

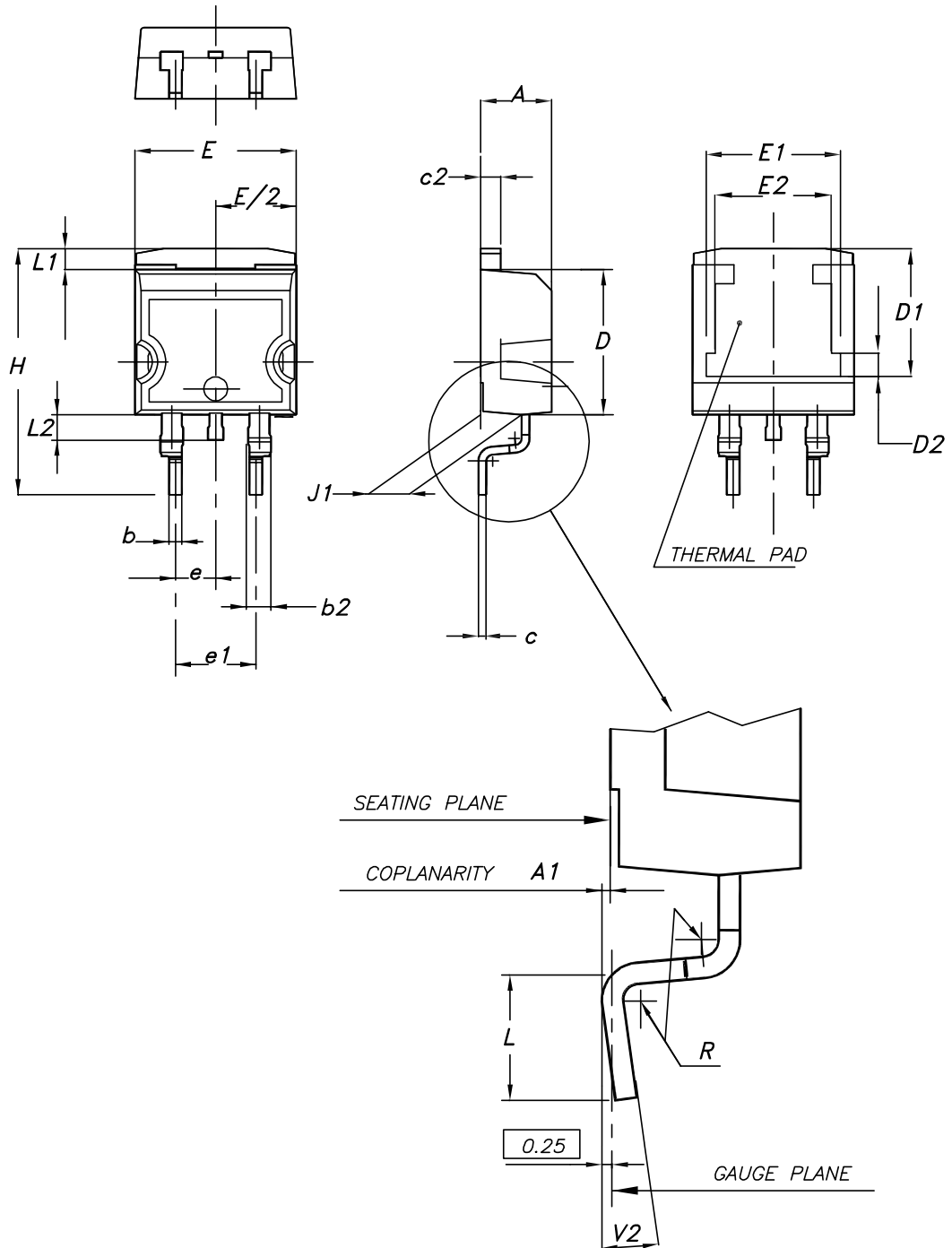
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In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.



### 4.1 D<sup>2</sup>PAK (TO-263) type A package information

Figure 21. D<sup>2</sup>PAK (TO-263) type A package outline

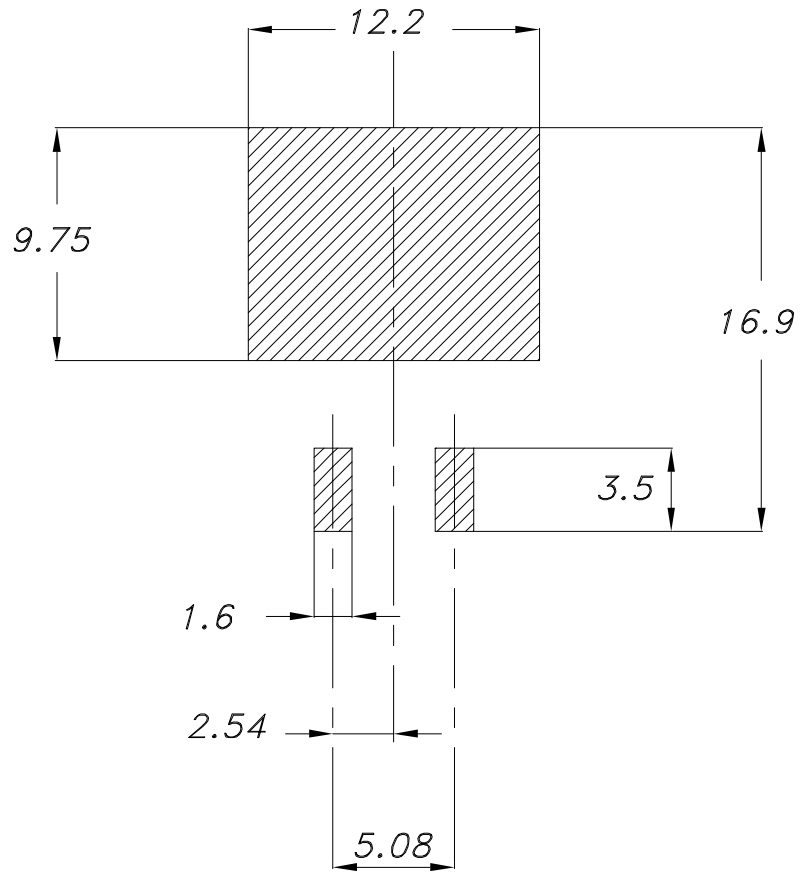


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**Table 9. D<sup>2</sup>PAK (TO-263) type A package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
c	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50	7.75	8.00
D2	1.10	1.30	1.50
E	10.00		10.40
E1	8.30	8.50	8.70
E2	6.85	7.05	7.25
e		2.54	
e1	4.88		5.28
H	15.00		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.40	
V2	0°		8°

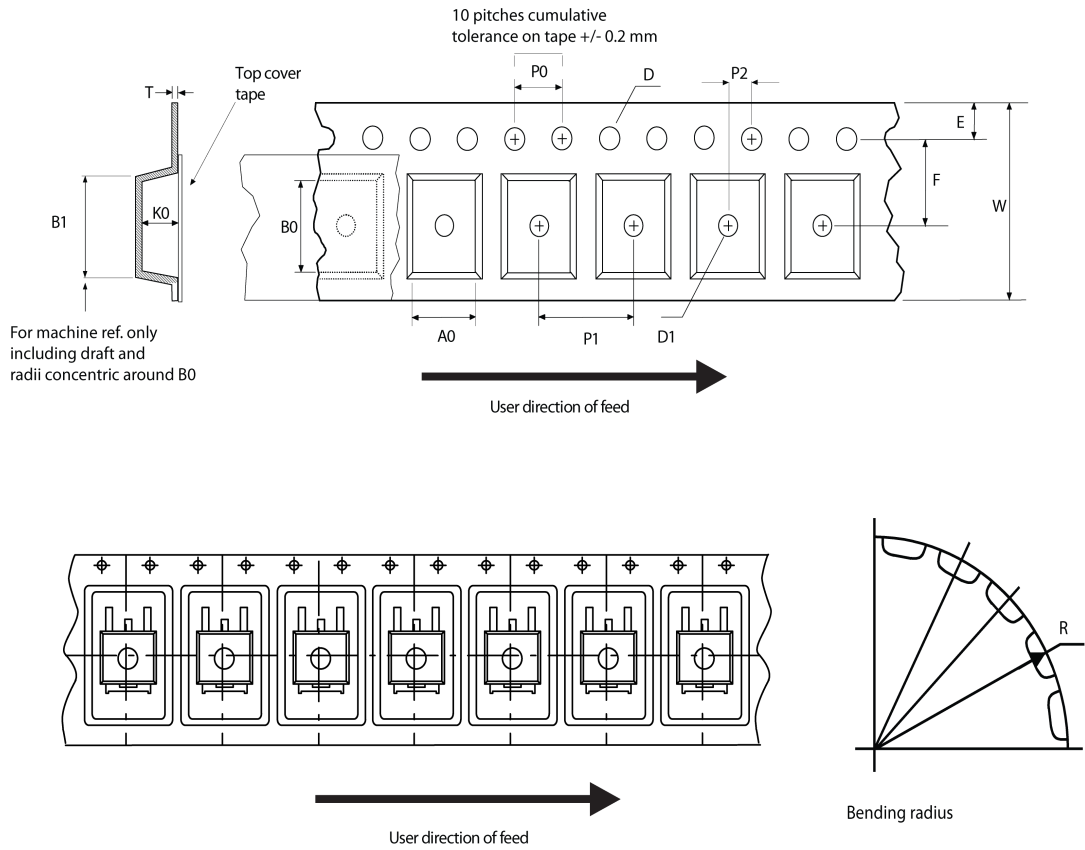
Figure 22. D<sup>2</sup>PAK (TO-263) recommended footprint (dimensions are in mm)



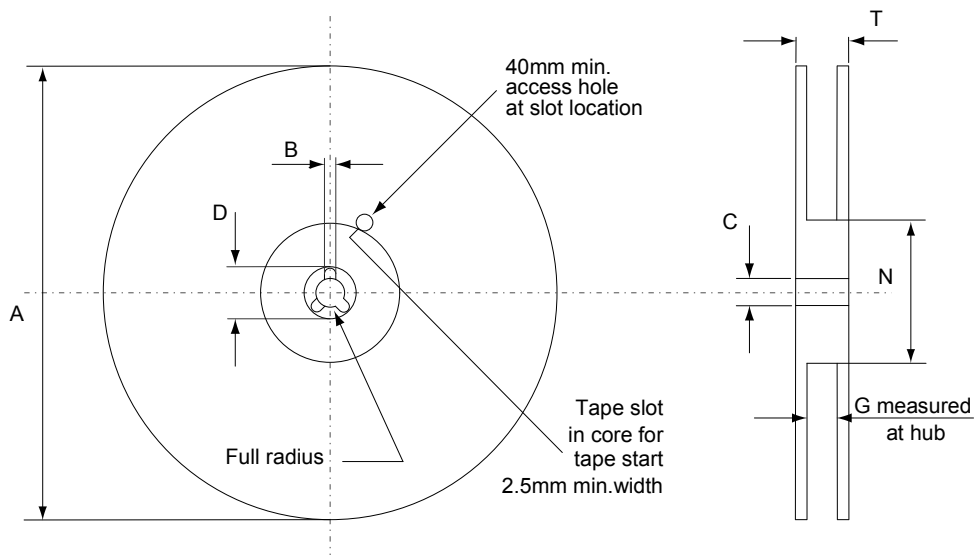
Footprint

## 4.2 D<sup>2</sup>PAK packing information

Figure 23. D<sup>2</sup>PAK tape outline



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**Figure 24. D<sup>2</sup>PAK reel outline**


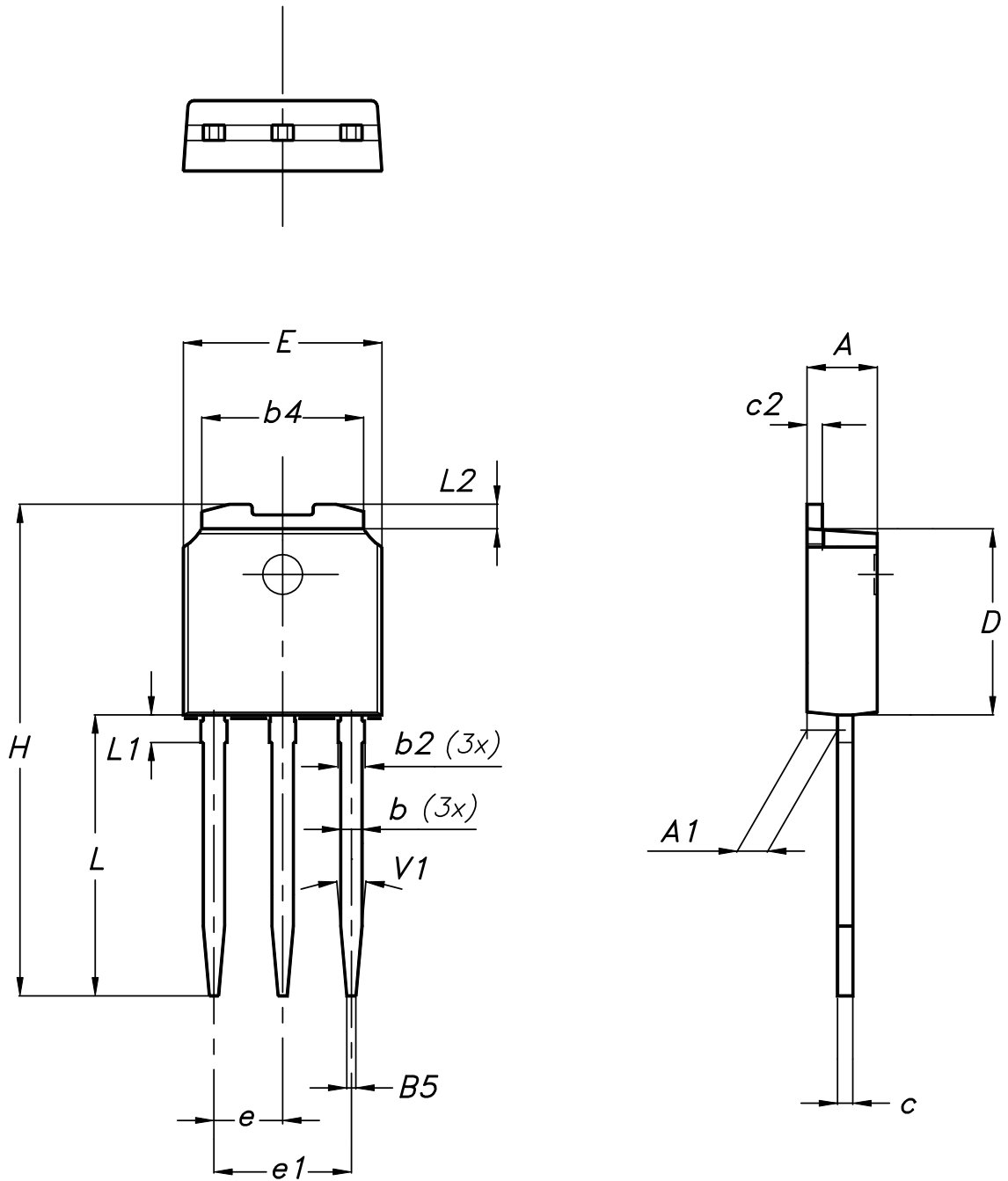
AM06038v1

**Table 10. D<sup>2</sup>PAK tape and reel mechanical data**

Tape			Reel			
Dim.	mm		Dim.	mm		
	Min.	Max.		Min.	Max.	
A0	10.5	10.7	A		330	
B0	15.7	15.9	B	1.5		
D	1.5	1.6	C	12.8	13.2	
D1	1.59	1.61	D	20.2		
E	1.65	1.85	G	24.4	26.4	
F	11.4	11.6	N	100		
K0	4.8	5.0	T		30.4	
P0	3.9	4.1	Base quantity Bulk quantity			
P1	11.9	12.1				1000
P2	1.9	2.1				1000
R	50					
T	0.25	0.35				
W	23.7	24.3				

### 4.3 IPAk (TO-251) type A package information

Figure 25. IPAk (TO-251) type A package outline



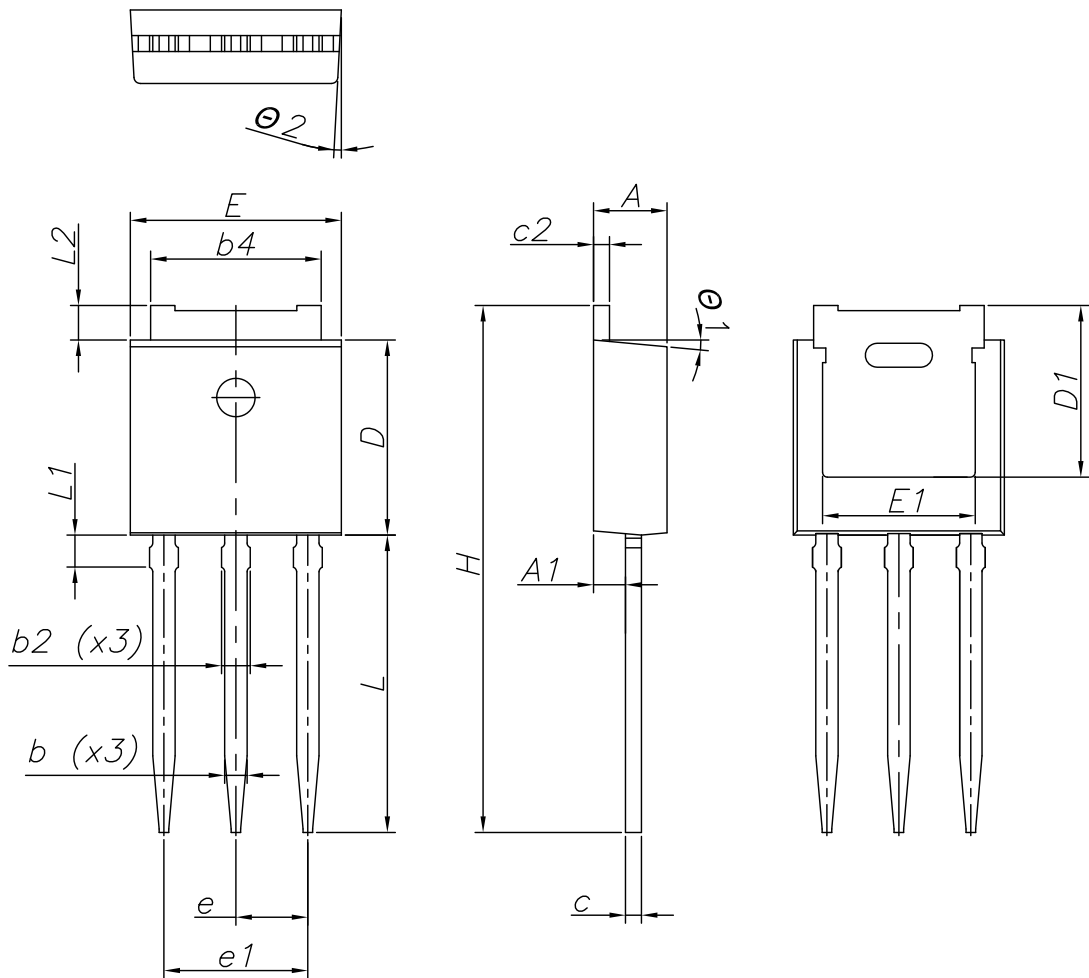
0068771\_IK\_typeA\_rev14

**Table 11. IPAK (TO-251) type A package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
b	0.64		0.90
b2			0.95
b4	5.20		5.40
B5		0.30	
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
E	6.40		6.60
e		2.28	
e1	4.40		4.60
H		16.10	
L	9.00		9.40
L1	0.80		1.20
L2		0.80	1.00
V1		10°	

#### 4.4 IPAk (TO-251) type C package information

Figure 26. IPAk (TO-251) type C package outline



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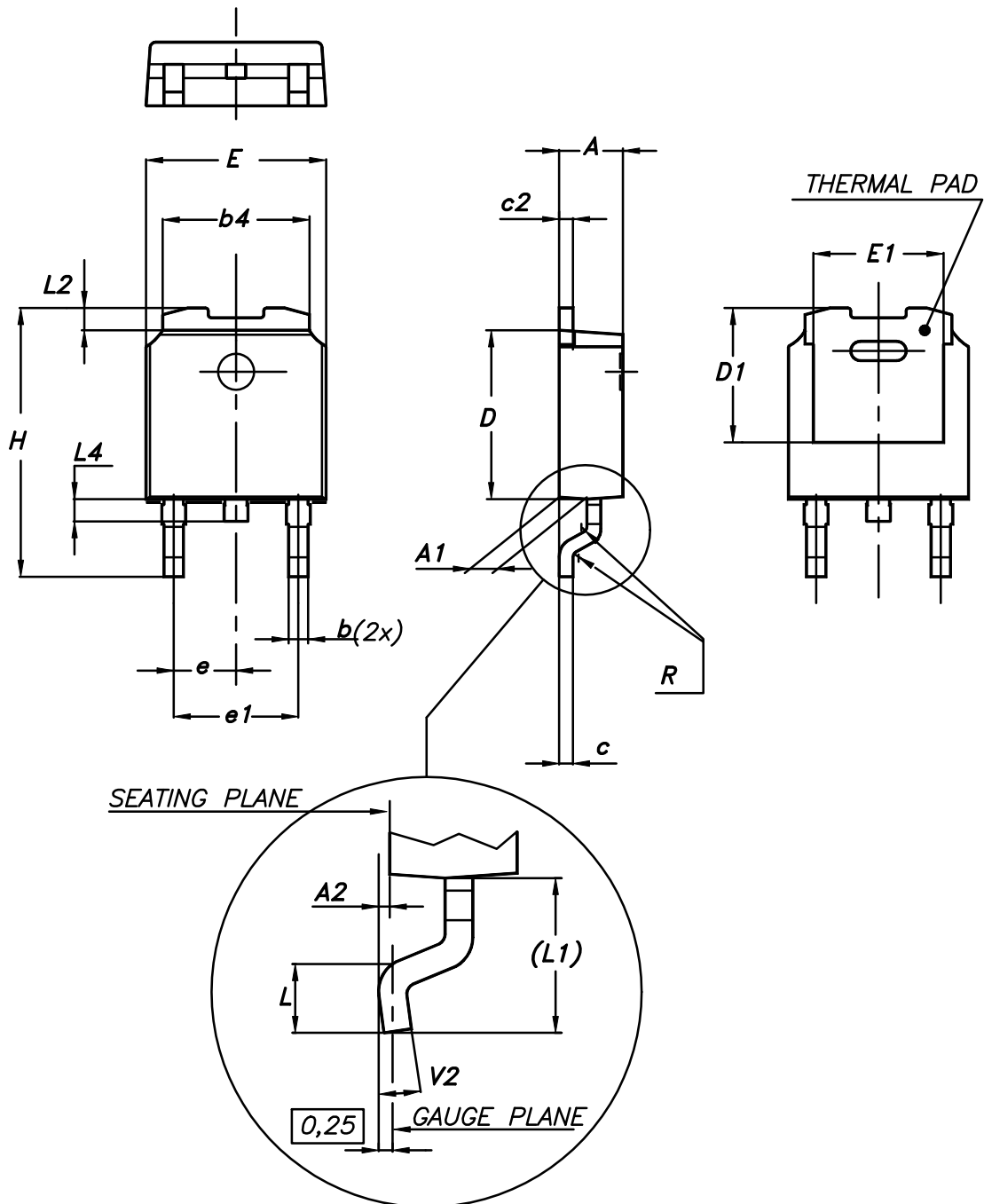


**Table 12. IPAK (TO-251) type C package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	2.20	2.30	2.35
A1	0.90	1.00	1.10
b	0.66		0.79
b2			0.90
b4	5.23	5.33	5.43
c	0.46		0.59
c2	0.46		0.59
D	6.00	6.10	6.20
D1	5.20	5.37	5.55
E	6.50	6.60	6.70
E1	4.60	4.78	4.95
e	2.20	2.25	2.30
e1	4.40	4.50	4.60
H	16.18	16.48	16.78
L	9.00	9.30	9.60
L1	0.80	1.00	1.20
L2	0.90	1.08	1.25
θ1	3°	5°	7°
θ2	1°	3°	5°

#### 4.5 DPAK (TO-252) type A package information

Figure 27. DPAK (TO-252) type A package outline



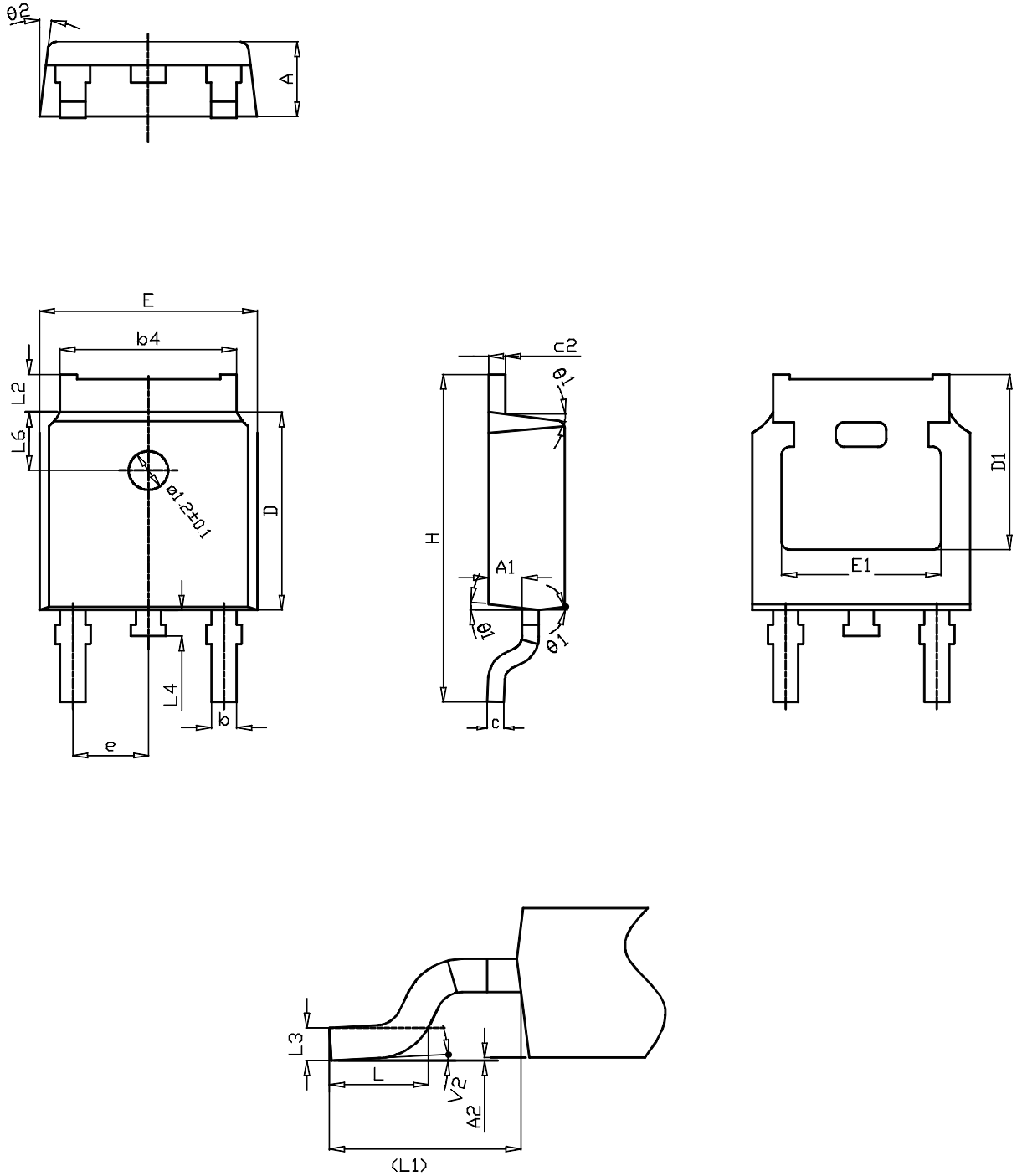
0068772\_A\_25

**Table 13. DPAK (TO-252) type A mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1	4.95	5.10	5.25
E	6.40		6.60
E1	4.60	4.70	4.80
e	2.159	2.286	2.413
e1	4.445	4.572	4.699
H	9.35		10.10
L	1.00		1.50
(L1)	2.60	2.80	3.00
L2	0.65	0.80	0.95
L4	0.60		1.00
R		0.20	
V2	0°		8°

### 4.6 DPAK (TO-252) type C package information

Figure 28. DPAK (TO-252) type C package outline



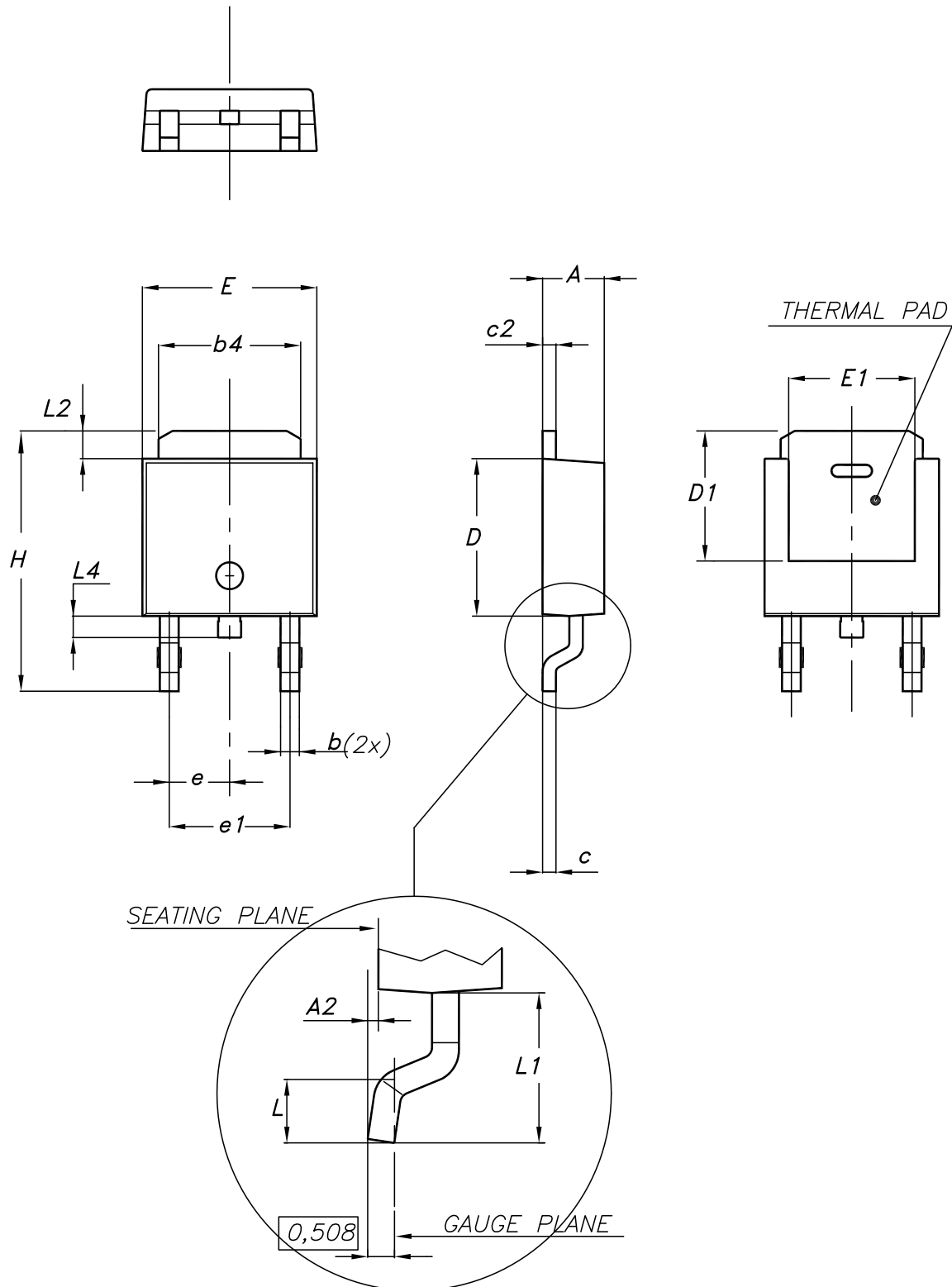
0068772\_C\_25

**Table 14. DPAK (TO-252) type C mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	2.20	2.30	2.38
A1	0.90	1.01	1.10
A2	0.00		0.10
b	0.72		0.85
b4	5.13	5.33	5.46
c	0.47		0.60
c2	0.47		0.60
D	6.00	6.10	6.20
D1	5.25		
E	6.50	6.60	6.70
E1	4.70		
e	2.186	2.286	2.386
H	9.80	10.10	10.40
L	1.40	1.50	1.70
L1	2.90 REF		
L2	0.90		1.25
L3	0.51 BSC		
L4	0.60	0.80	1.00
L6	1.80 BSC		
θ1	5°	7°	9°
θ2	5°	7°	9°
V2	0°		8°

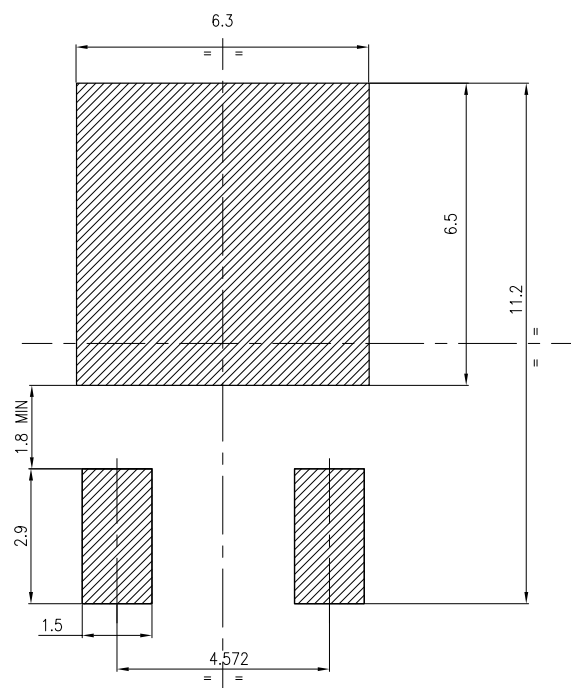
### 4.7 DPAK (TO-252) type E package information

Figure 29. DPAK (TO-252) type E package outline



**Table 15. DPAK (TO-252) type E mechanical data**

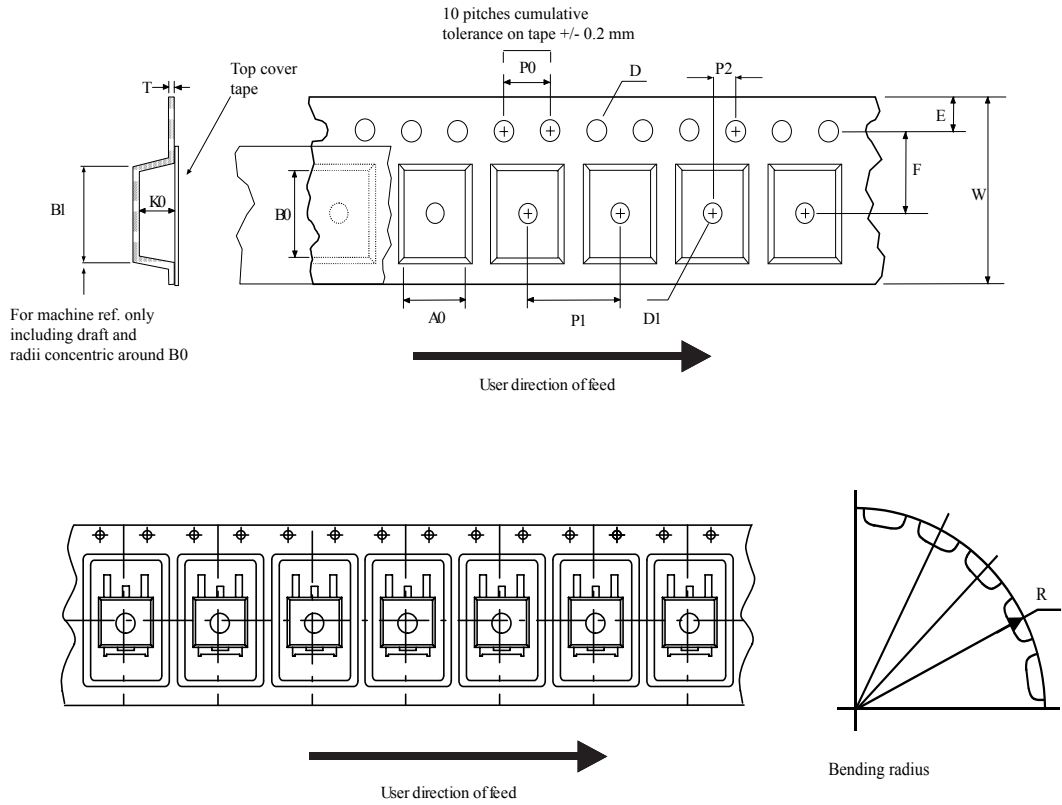
Dim.	mm		
	Min.	Typ.	Max.
A	2.18		2.39
A2			0.13
b	0.65		0.884
b4	4.95		5.46
c	0.46		0.61
c2	0.46		0.60
D	5.97		6.22
D1	5.21		
E	6.35		6.73
E1	4.32		
e		2.286	
e1		4.572	
H	9.94		10.34
L	1.50		1.78
L1		2.74	
L2	0.89		1.27
L4			1.02

**Figure 30. DPAK (TO-252) recommended footprint (dimensions are in mm)**


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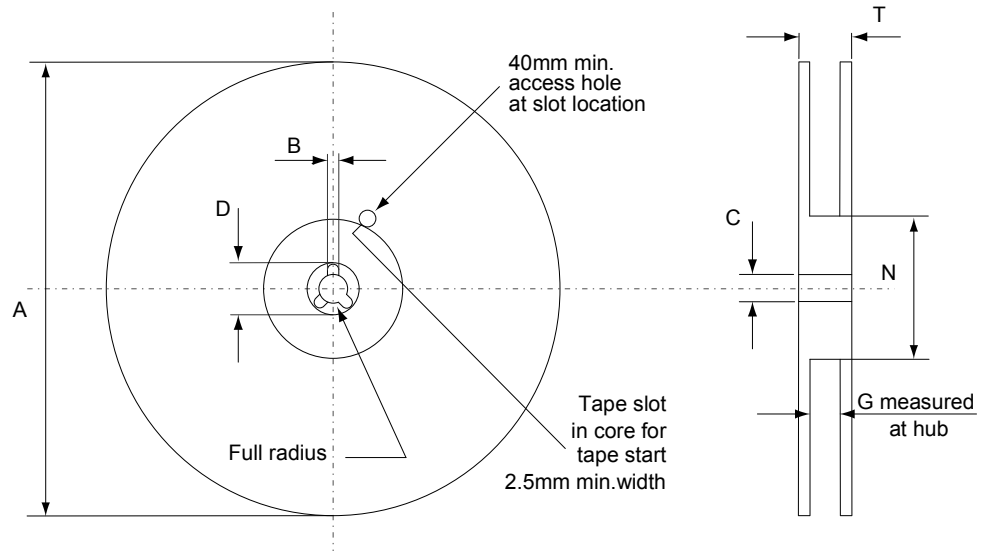
## 4.8 DPAK (TO-252) packing information

Figure 31. DPAK (TO-252) tape outline



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**Figure 32. DPAK (TO-252) reel outline**


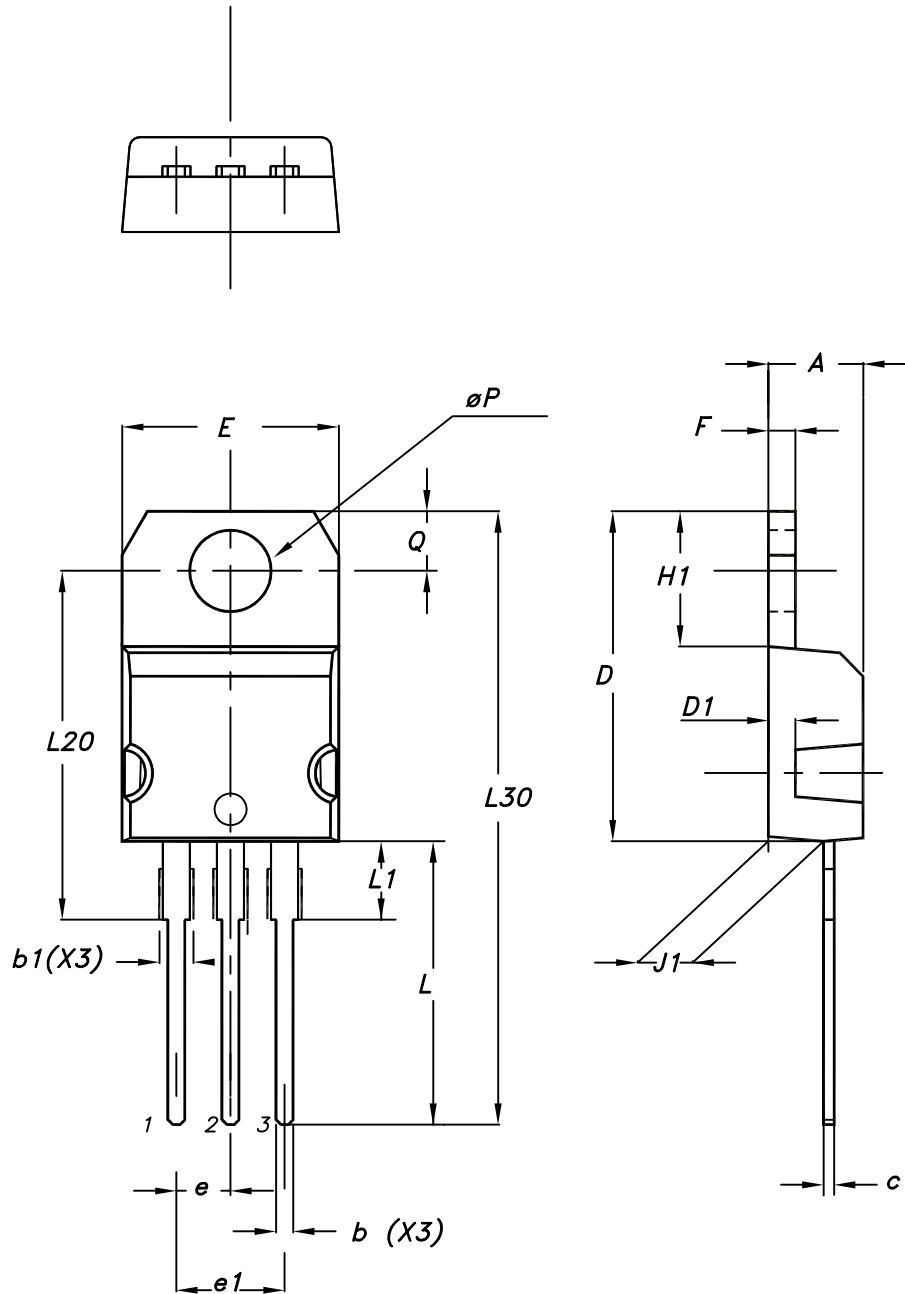
AM06038v1

**Table 16. DPAK (TO-252) tape and reel mechanical data**

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	6.8	7	A		330
B0	10.4	10.6	B	1.5	
B1		12.1	C	12.8	13.2
D	1.5	1.6	D	20.2	
D1	1.5		G	16.4	18.4
E	1.65	1.85	N	50	
F	7.4	7.6	T		22.4
K0	2.55	2.75			
P0	3.9	4.1	Base qty.		2500
P1	7.9	8.1	Bulk qty.		2500
P2	1.9	2.1			
R	40				
T	0.25	0.35			
W	15.7	16.3			

## 4.9 TO-220 type A package information

Figure 33. TO-220 type A package outline



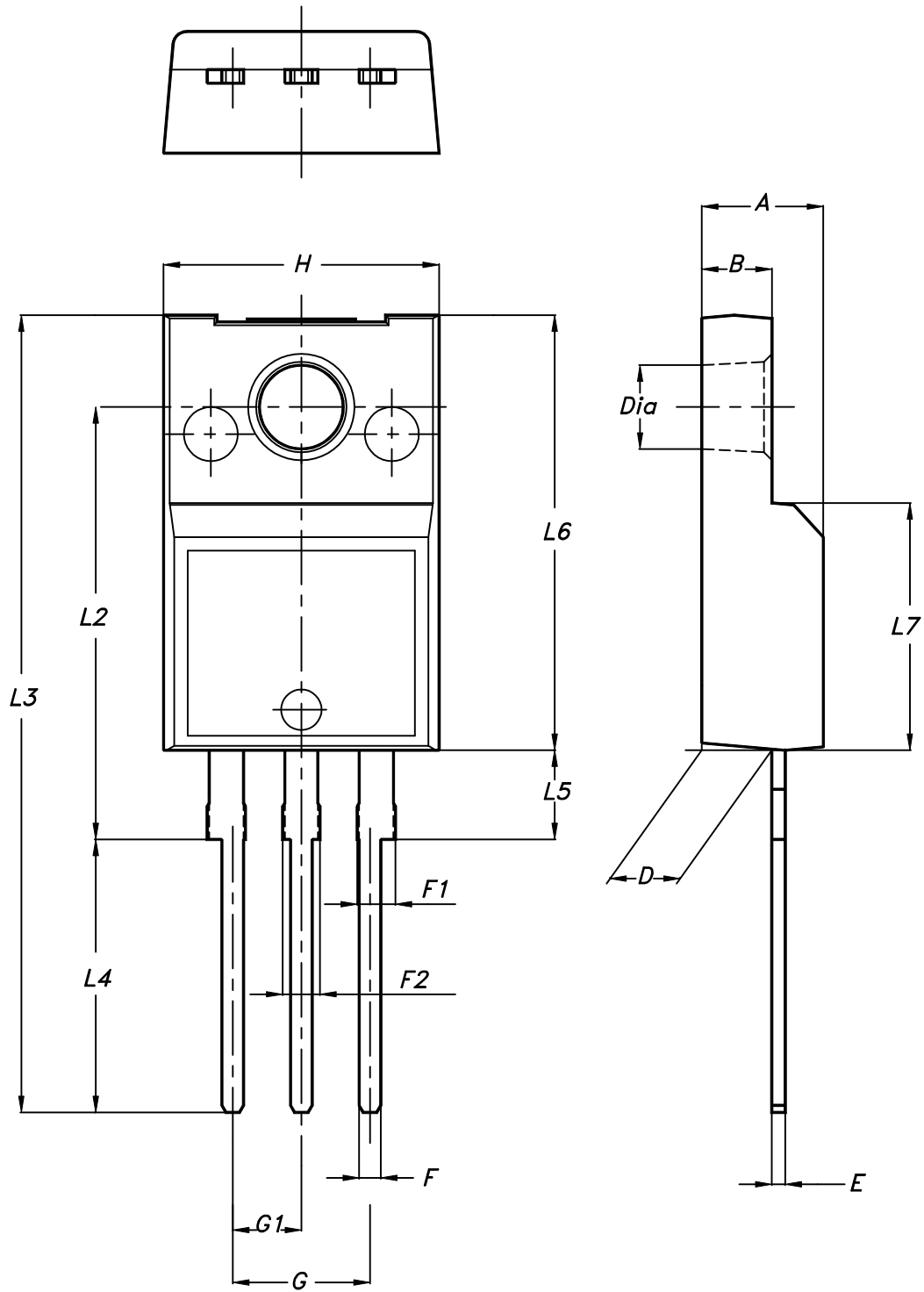
0015988\_typeA\_Rev\_21

**Table 17. TO-220 type A package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.55
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10.00		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13.00		14.00
L1	3.50		3.93
L20		16.40	
L30		28.90	
øP	3.75		3.85
Q	2.65		2.95

4.10 TO-220FP package information

Figure 34. TO-220FP package outline



7012510\_Rev\_12\_B

**Table 18. TO-220FP package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.4		4.6
B	2.5		2.7
D	2.5		2.75
E	0.45		0.7
F	0.75		1
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.2
G1	2.4		2.7
H	10		10.4
L2		16	
L3	28.6		30.6
L4	9.8		10.6
L5	2.9		3.6
L6	15.9		16.4
L7	9		9.3
Dia	3		3.2

## 5 Ordering information

Table 19. Order codes

Order code	Marking	Package	Packing
STB3NK60ZT4	B3NK60Z	D <sup>2</sup> PAK	Tape and reel
STD3NK60Z-1	D3NK60Z	IPAK	Tube
STD3NK60ZT4		DPAK	Tape and reel
STP3NK60Z	P3NK60Z	TO-220	Tube
STP3NK60ZFP	P3NK60ZFP	TO-220FP	Tube

## Revision history

**Table 20. Document revision history**

Date	Version	Changes
07-Jul-2003	5	Updated document.
20-Aug-2018	6	Updated <a href="#">Section 1 Electrical ratings</a> , <a href="#">Section 2 Electrical characteristics</a> and <a href="#">Section 4 Package information</a> . Minor text changes.

## Contents

<b>1</b>	<b>Electrical ratings</b> .....	<b>2</b>
<b>2</b>	<b>Electrical characteristics</b> .....	<b>3</b>
<b>2.1</b>	Electrical characteristics curves .....	<b>5</b>
<b>3</b>	<b>Test circuits</b> .....	<b>8</b>
<b>4</b>	<b>Package information</b> .....	<b>9</b>
<b>4.1</b>	D <sup>2</sup> PAK (TO-263) type A package information .....	<b>9</b>
<b>4.2</b>	D <sup>2</sup> PAK packing information .....	<b>12</b>
<b>4.3</b>	IPAK (TO-251) type A package information .....	<b>14</b>
<b>4.4</b>	IPAK (TO-251) type C package information .....	<b>16</b>
<b>4.5</b>	DPAK (TO-252) type A package information .....	<b>18</b>
<b>4.6</b>	DPAK (TO-252) type C package information .....	<b>20</b>
<b>4.7</b>	DPAK (TO-252) type E package information .....	<b>22</b>
<b>4.8</b>	DPAK (TO-252) packing information .....	<b>24</b>
<b>4.9</b>	TO-220 type A package information .....	<b>26</b>
<b>4.10</b>	TO-220FP package information .....	<b>28</b>
<b>5</b>	<b>Ordering information</b> .....	<b>31</b>
	<b>Revision history</b> .....	<b>32</b>





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